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<u>Agenda</u>

- Background / Capabilities
- Characterization Platform
- Characterization Approach
- Enterprise Usage Model
- Flash Endurance Example
- Increased Focus on Read Disturbs
- Additional Areas of Analysis
- Requests for Suppliers
- Summary



Background

- In-depth knowledge of Flash technology characteristics is needed to maximize performance and manage reliability for Enterprise Systems designs
- Driving to establish center of competence for Flash characterization supporting enterprise usage
- Support development and verification of Flash management schemes through characterization

Capabilities

- Perform supplier / technology comparisons and competitive analyses on common platform
- Provide in-depth understanding of Flash technology features and functions
- Identify strengths and weaknesses of leading-edge Flash technologies based on enterprise usage cases
- Assess new technologies and investigate approaches to improve performance / extend
 Flash reliability



Characterization Platform

- Flash test node (2 shown)
- Node includes 4 Flash test stations
- Up to 256 dice available for test



Node controller manages power & thermal for 4 Flash test stations
Thermal controllers drive external heaters

Power control provided for ZC702





- Flash test station
- Xilinx ZC702 FPGA evaluation board
- 2 Flash daughter cards (one 16DP per card)
- Resistive thermal heater



Characterization Approach

- Perform extended testing across technology process
 - Endurance
 - Data retention
 - Read disturb
- Evaluate key parametrics
 - Array timings
 - Power consumption
 - AC timings
- Additional experiments based on enterprise usage cases





Enterprise Usage Model

- Initially SLC, next Enterprise MLC, now enhanced Commercial MLC raw NAND
 - Cost management and industry Flash management capabilities driving transitions
- High endurance and optimized data retention
- Largest available die density
- Widely distributed designs maximize Flash subsystem performance and not device I/O speed
- Power management now increasingly important with high capacity systems
- Advanced packaging requiring enterprise quality



IBM FlashSystem 840



Flash Endurance Example (Similar Technology Node)



- Seek improved raw endurance for commercial MLC devices
- Apply additional capabilities to extend endurance further



Increased Focus on Read Disturbs

- Read disturb characteristics:
 - When cell is read, other cells on same bit line weakly programmed
 - Repeated reads without erase may cause cells to shift enough to change state
 - More pronounced in smaller technology nodes
 - Block erase resets read disturb exposure
- Read disturb characterization approach:
 - Pre-cycling followed by read disturb testing
 - Record errors at end of read cycling as well as at intermediate points
 - Apply appropriate temperature to evaluate usage case for pre-cycling and read disturb testing



Source: Micron



Additional Areas of Analysis

- Exhaustive testing to point-of-failure
- Process window / lot variation investigations
- System duty cycle / dwell time-related experiments
- Workload / command sequence robustness checks
- Typical power evaluation based on design attributes



PE Cycles



Requests to Suppliers

- Improve specifications including all supporting documentation
- Open test mode access to further extend Flash viability
- Continue to pursue reliability improvements in support of enterprise
- Seek power consumption improvements with new designs
- Enable 3D NAND with advanced capabilities if technology warrants





<u>Summary</u>

- In-depth knowledge of Flash technology characteristics is needed to maximize performance and manage reliability for Enterprise Systems designs
- Driving to establish center of competence for Flash characterization supporting enterprise usage
- Increased focus on commercial MLC endurance and read disturb capabilities is required for enterprise
- Suppliers are requested to improve specifications, open test modes, continue to pursue reliability improvements, reduce power consumption and aggressively enable 3D technologies going forward